



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



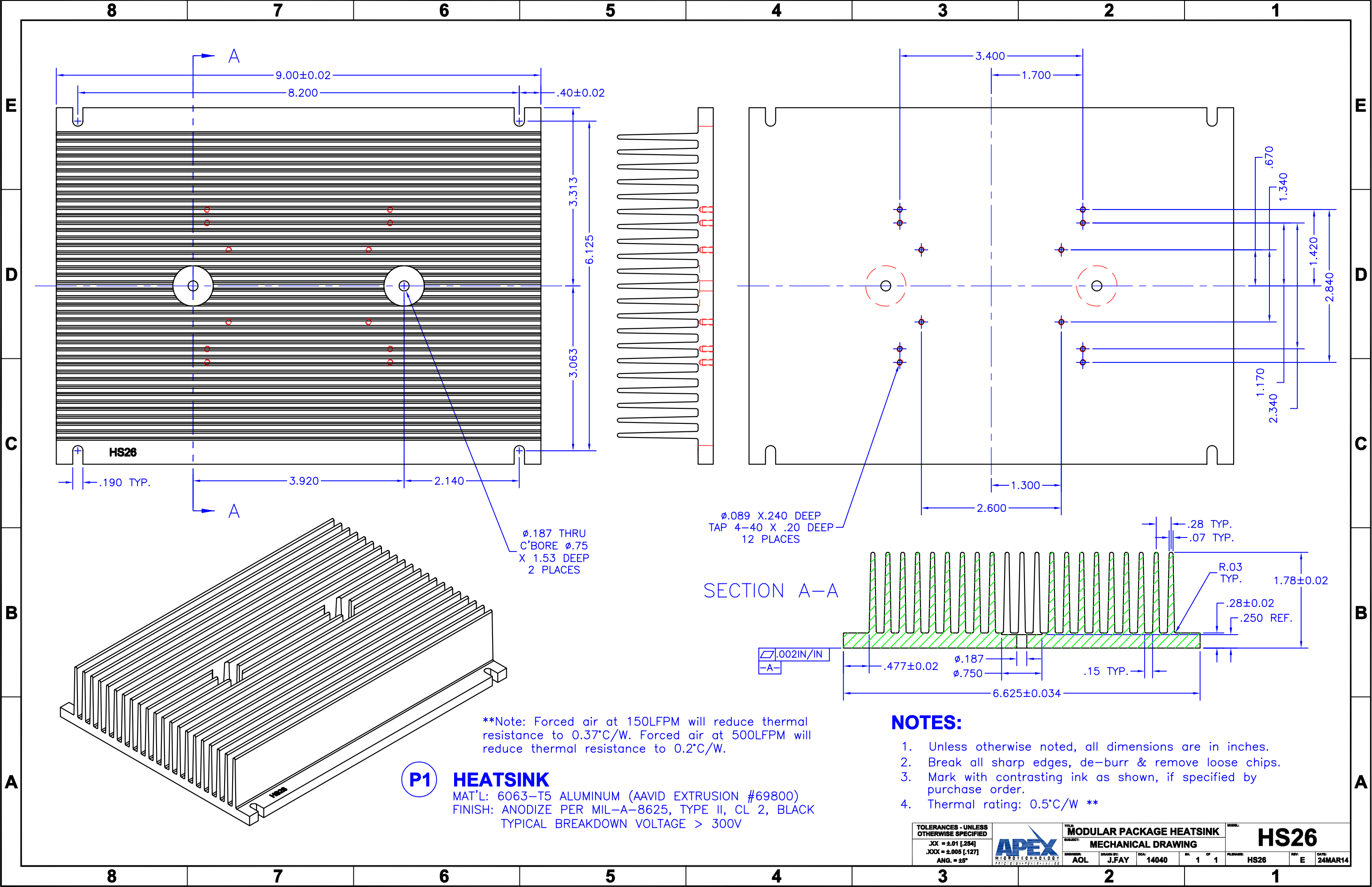
## Contact us

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\*\*Note: Forced air at 150LFPM will reduce thermal resistance to 0.37°C/W. Forced air at 500LFPM will reduce thermal resistance to 0.2°C/W.

**P1 HEATSINK**  
 MAT'L: 6063-T5 ALUMINUM (AAVID EXTRUSION #69800)  
 FINISH: ANODIZE PER MIL-A-8625, TYPE II, CL 2, BLACK  
 TYPICAL BREAKDOWN VOLTAGE > 300V

- NOTES:**
1. Unless otherwise noted, all dimensions are in inches.
  2. Break all sharp edges, de-burr & remove loose chips.
  3. Mark with contrasting ink as shown, if specified by purchase order.
  4. Thermal rating: 0.5°C/W \*\*

|   |  |                          |                 |                      |            |
|---|--|--------------------------|-----------------|----------------------|------------|
| TOLERANCES - UNLESS OTHERWISE SPECIFIED |  | TITLE                    |                 | MODEL                |            |
| JXX = ±0.01 [254]                       |  | MODULAR PACKAGE HEATSINK |                 | HS26                 |            |
| JXX = ±0.005 [127]                      |  | MECHANICAL DRAWING       |                 | REV: E DATE: 24MAR14 |            |
| ANG. = ±5°                              |  | ENGINEER: AOL            | DRAWN BY: J.FAY | DWG. NO: 14040       | BL. 1 OF 1 |
| APEX MICROTECHNOLOGY                    |  | AOL                      |                 | HS26                 |            |